

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appln. No: 10/001,421  
Applicant: Joseph M. Milewski et al.  
Filed: November 2, 2001  
Title: LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE  
TC/A.U.: 2811  
Examiner: Hung K. Vu  
Confirmation No.: 4204  
Docket No.: END919970013US2

**SUBMISSION OF FORMAL DRAWINGS**

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Responsive to the requirement dated September 24, 2004, for the submission of formal drawings in the above-identified application, formal drawings are submitted herewith.

Respectfully submitted,

RatnerPrestia

  
Lawrence E. Ashery, Reg. No. 34,515  
Attorney for Applicants

LEA/pb

Enclosure: (3) Sheets of Drawings

Dated: October 27, 2004

Suite 301  
One Westlakes, Berwyn  
P.O. Box 980  
Valley Forge, PA 19482-0980  
(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 09-0457 (IBM Corporation) of any fees associated with this communication.